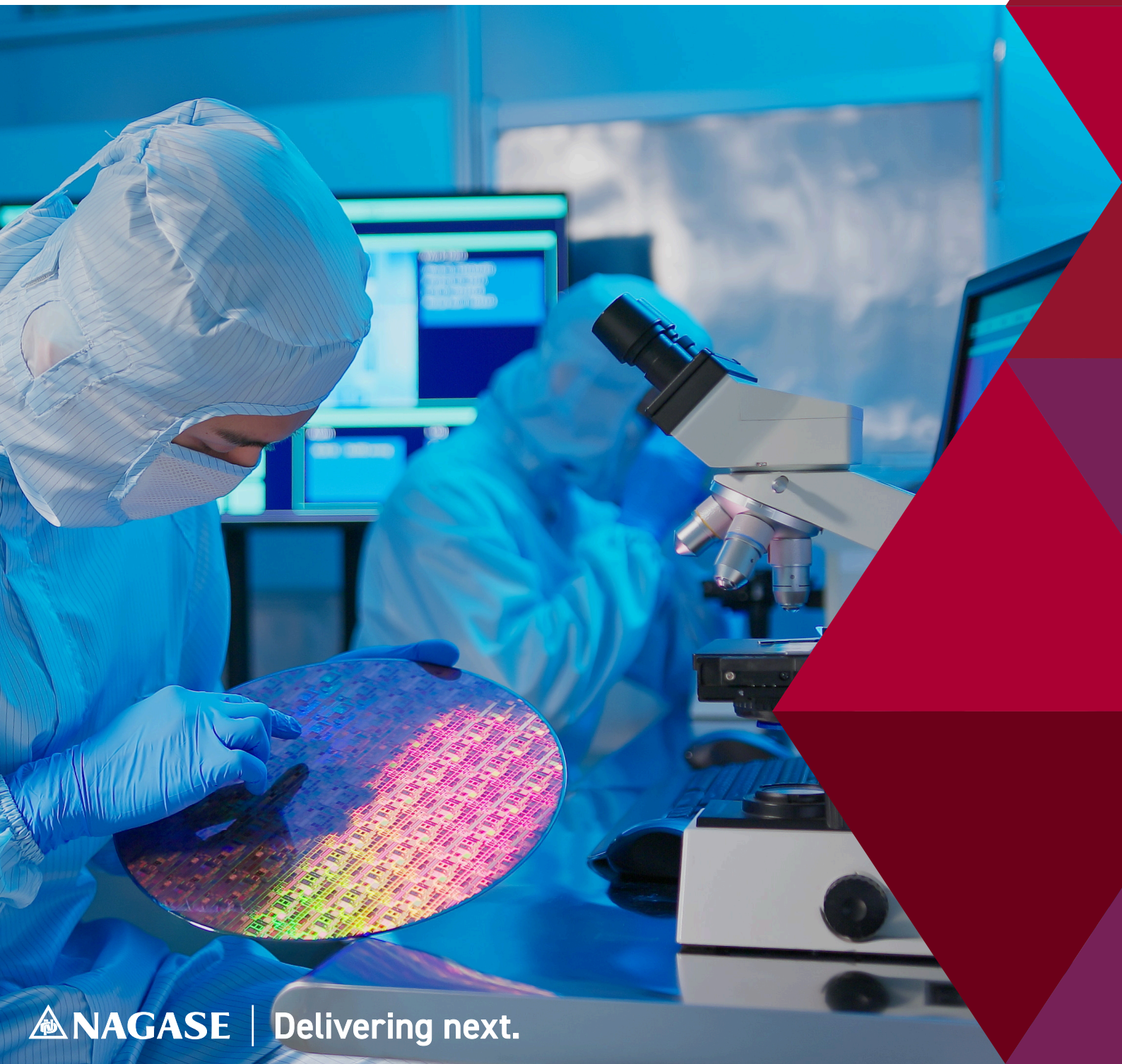


 Materials for Power Devices and Electronic Components

Megasonic Wafer Cleaning

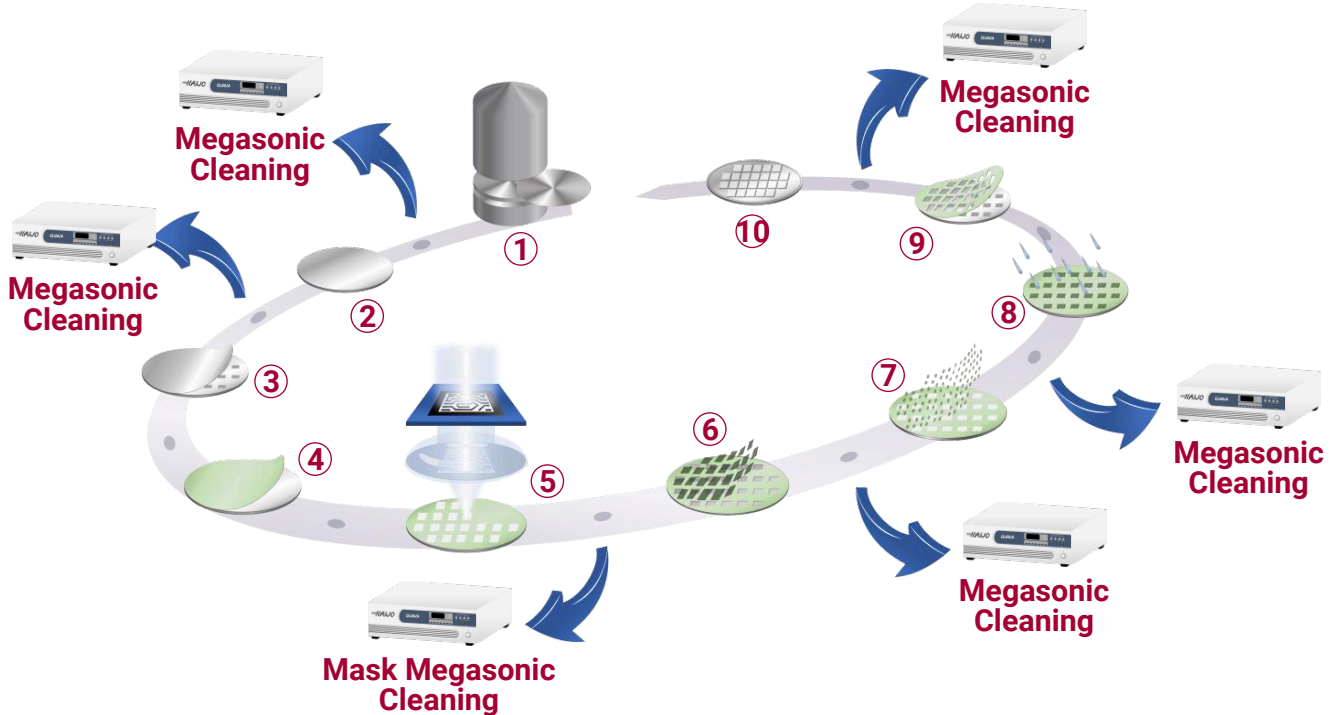


Ultrasonic Cleaning Systems

The Megasonic Cleaning Process is used to remove dust and dirt from silicon wafers in order to prevent damage to the material

Wafer Fabrication Steps

It is estimated that around 40 % of semiconductor production is attributable to cleaning processes.



- | | | |
|---------------------------------|---------------|---------------------|
| 1. Single-Crystal Silicon Ingot | 5. Exposure | 8. Ion Implantation |
| 2. Polishing | 6. Developing | 9. Stripping |
| 3. Deposition | 7. Etching | 10. Processed Wafer |
| 4. Photoresist Coating | | |

Product Line Up

Our products cover from 19.5 kHz at lowest to 3 Mhz at highest.

